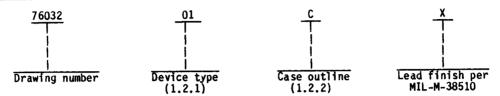
Device 01 inactive for new		REVISIONS		
design as of 22 September 1978. Use M38510/31501B	LTR	DESCRIPTION	DATE	APPROVED
-	С	Revised to military drawing format. Delete vendors: CAGE 07263, 27014, and 18324. Add note for no approved source available for packages A and B. Add LCC package, case outline 2. Table I, $f_{MAX}$ (A to $Q_A$ , $C_L$ = 15 pF, 10 and 11); change 20 MHz to 19 MHz. (50 pF, 10 and 11); change 23 MHz to 18 MHz. (B to $Q_B$ , $C_L$ = 15 pF, 10 and 11); change from 11 MHz to 10 MHz. Change I $_{IH3}$ , 40 $_{\mu}$ A to 80 $_{\mu}$ A, I $_{IH4}$ , 200 $_{\mu}$ A to 400 $_{\mu}$ A, I $_{IH5}$ , 80 $_{\mu}$ A to 160 $_{\mu}$ A, I $_{IH6}$ , 400 $_{\mu}$ A to 800 $_{\mu}$ A. Add logic diagram. Change CAGE number to 67268.	5 Oct 1987	Reman

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- 1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".
  - 1.2 Part number. The complete part number shall be as shown in the following example:



1.2.1 Device type. The device type shall identify the circuit function as follows:

Device type Generic number Circuit

01 54LS90 Decade counter

1.2.2 <u>Case outlines</u>. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows:

 Outline letter
 Case outline

 A
 F-1 (14-lead, 1/4" x 1/4"), flat package

 B
 F-3 (14-lead, 3/16" x 1/4"), flat package

 C
 D-1 (14-lead, 1/4" x 3/4"), dual-in-line package

 D
 F-2 (14-lead, 1/4" x 3/8"), flat package

 C
 (20-terminal, .350" x .350"), square chip carrier

 package
 LCC + Ple - 20

1.3 Absolute maximum ratings.

1.4 Recommended operating conditions.

1/ Must withstand the added Pp due to short circuit test (e.g., Ios).

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### 2. APPLICABLE DOCUMENTS

2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

### **SPECIFICATION**

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

**STANDARD** 

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

- 2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.
  - 3. REQUIREMENTS
- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- 3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
  - 3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.
  - 3.2.2 Truth tables. The truth tables shall be as specified on figure 2.
  - 3.2.3 Logic diagram. The logic diagram shall be as specified on figure 3.
  - 3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.
- 3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full recommended case operating temperature range.
- 3.4 Marking. Marking shall be in accordance with MIL-STD $\sim$ 883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein.
- 3.5 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD $\pm$ 883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.7 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).

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TABL	E I. Elec	trical performance characteristi	cs.				
Test	   Symbol		   Group A    subgroups			Unit	
	1	unless otherwise specified		Min	Max 	<u> </u>	
High-level output voltage	! ! v <sub>OH</sub> !	$V_{CC} = 4.5 \text{ V}$ $I_{OH} = -0.4 \text{ mA}$ $V_{IH} = 2.0 \text{ V}$ $V_{IL} = 0.7 \text{ V}$	1, 2, 3	2.5	 	٧	
Low-level output voltage	   V <sub>OL</sub> 	V <sub>CC</sub> = 4.5 V I <sub>OL</sub> = 4.0 mA V <sub>IH</sub> = 2.0 V V <sub>IL</sub> = 0.7 V	1, 2, 3		0.4	<b>V</b>	
Input clamp voltage	VIC	V <sub>CC</sub> = 4.5 V; I <sub>IN</sub> = ~18 mA	1		-1.5	V	
Input current at reset inputs	I <sub>IH1</sub>	V <sub>CC</sub> = 5.5 V; V <sub>IH</sub> = 2.7 V	1, 2, 3		   20 	μ <b>Α</b>	
	I IH2	   V <sub>CC</sub> = 5.5 V; V <sub>IH</sub> = 5.5 V	1, 2, 3	 	   100 	l I μA	
	IIIL1	V <sub>CC</sub> = 5.5 V; V <sub>IL</sub> = 0.4 V	1, 2, 3		-0.4	l ImA I	
Input current at A input	I <sub>IH3</sub>	V <sub>CC</sub> = 5.5 V; V <sub>IH</sub> = 2.7 V	1, 2, 3		   80 	   μ <b>Α</b> 	
	I IH4	V <sub>CC</sub> = 5.5 V; V <sub>IH</sub> = 5.5 V	1, 2, 3		400	μA	
	I <sub>IL2</sub>	V <sub>CC</sub> = 5.5 V; V <sub>IL</sub> = 0.4 V	1, 2, 3		-2.4	l mA	
Input current at B input	I <sub>IH5</sub>	V <sub>CC</sub> = 5.5 V; V <sub>IH</sub> = 2.7 V	1, 2, 3	   	160	Ι   μΑ 	
	I IH6	V <sub>CC</sub> = 5.5 V; V <sub>IH</sub> = 5.5 V	1, 2, 3	l 	800	l LμA	
	IIL3	V <sub>CC</sub> = 5.5 V; V <sub>IL</sub> = 0.4 V	1, 2, 3	 	-3.2	l mA	
Short-circuit output current	Ios	V <sub>CC</sub> = 5.5 V V <sub>OUT</sub> = 0.0 V <u>1</u> /	1, 2, 3	   ~15 	  -130 	lmA lmA	
Supply current	Icc	V <sub>CC</sub> = 5.5 V	1, 2, 3	l l l	15	l mA	
Functional tests			1 7	}   	l   	 	

See footnotes at end of table.

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Test	Symbol		onditions	Group A	lim	its	   Unit
iest		-55°C <	T <sub>C</sub> < +125°C erwise specified	subgroups	Min	Max	     
Maximum clock frequency from A to Q <sub>A</sub>	f <sub>MAX1</sub>	V <sub>CC</sub> = 5.0 V  R <sub>L</sub> = 2 kΩ ±5%		9	32		   MHz 
Tron A to 4A	İ	<u>2</u> /		10, 11	19	<u> </u>	<del> </del>
	İ	i i	C <sub>L</sub> = 50 pF ±10%	9	28	<del> </del>	MHz 
		- -		10, 11	18	+	<del> </del>
Maximum clock frequency from B to $Q_{\rm B}$	f <sub>MAX2</sub>		C <sub>L</sub> = 15 pF ±10%	9	16	<u> </u> 	MHz
110m p 00 4B	į			10, 11	10	1	<u> </u>
	į		C <sub>L</sub> = 50 pF ±10%	9	11	1	i MHz
		<u>.</u>		10, 11	6	<del> </del>	<del> </del>
Propagation delay time, from A to $\mathbb{Q}_{\mathbb{A}}$	t <sub>PHL1</sub>		C <sub>L</sub> = 15 pF ±10%	9	i T	18	l ns
		į		10, 11	<u> </u> 	25	1
		İ	C <sub>L</sub> = 50 pF ±10%	9	<u> </u>	23	ns
	<u> </u>	-		10, 11	<u> </u>	32	<u> </u>
	t <sub>PLH1</sub>		C <sub>L</sub> = 15 pF ±10%	9	<u> </u>	16	İ ns
		İ		10, 11	<u>i</u>	j 22	<u> </u>
			C <sub>L</sub> = 50 pF ±10%	9	<u>i</u>	21	ns
		<u> </u>	<u> </u>	10, 11	<u> </u>	29	<u> </u>
Propagation delay time,	t <sub>PHL2</sub>		C <sub>L</sub> = 15 pF ±10%	9	<u> </u>	50	i ns
from A to Q <sub>D</sub>				10, 11	<u> </u>	70	<del> </del>
		 	C <sub>L</sub> = 50 pF ±10%	9	İ	55	i ns
		1		10, 11	<u> </u>	77	<del> </del>
	t <sub>PLH2</sub>		C <sub>L</sub> = 15 pF ±10%	9		48	ns
				10, 11	<u> </u>	67	<u> </u>
	!		C <sub>L</sub> = 50 pF ±10%	9	<u> </u>	53	ns
				10, 11	! 	   74	1

See footnotes at end of table.

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TABLE I	. Electrica	l performance characteristics - C	ontinued.			
Test	Symbol	Conditions Conditions Conditions Conditions Conditions Conditions Conditions Conditions Conditions Conditions Conditions Conditions Conditions Conditions Conditions Conditions Conditions Conditions Conditions Conditions	Group A    subgroups	Lim	Unii	
		unless otherwise specified	subgroups	Min	Max	<u> </u> 
Propagation delay time,	t <sub>PHL3</sub>		9		21	ns
from B to $Q_{\mathrm{B}}$		2/	10, 11		29	<u> </u>
	1	C <sub>L</sub> = 50 pF ±10%	9		26	ns
	ļ		10, 11		36	<u> </u>
	t <sub>PLH3</sub>	C <sub>L</sub> = 15 pF ±10%	9		16	ns
			10, 11		22	<u> </u>
	1	C <sub>L</sub> = 50 pF ±10%	9		21	ns
· · · · · · · · · · · · · · · · · · ·			10, 11		29	ļ
Propagation delay time, from B to Q <sub>C</sub>	tpHL4		9		35	ns
Trom B to QC		<u> </u>	10, 11		149	<u> </u>
		C <sub>L</sub> = 50 pF ±10%	9		40	ns
	<u> </u>		10, 11		56	<u> </u>
	t <sub>PLH4</sub>	C <sub>L</sub> = 15 pF ±10%	9		32	ns
	ļ		10, 11		45	ļ
	3   		9		37	ns
			10, 11		52	<u> </u>
Propagation delay time,	t <sub>PHL</sub> 5	  C <sub>L</sub> = 15 pF ±10%	9		35	l ns
from B to Q <sub>D</sub>			10, 11		49	
	!		9		40	l   ns
			10, 11		56	ļ
	t <sub>PLH5</sub>	$C_{L} = 15 \text{ pF } \pm 10\%$	9		32	i ns
			10, 11		45	1
			9		37	ns
		1	10, 11		52	1

See footnotes at end of table.

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Test	Symbol Symbol	Conditions   -55°C < T <sub>C</sub> < +125°C	Group A	Lim	Unit		
		-55°C < T <sub>C</sub> < +125°C   unless otherwise specified 	subgroups	Min	Max		
Propagation delay time,	t <sub>PHL6</sub>	V <sub>CC</sub> = 5.0 V   C <sub>L</sub> = 15 pF ±10%	9		40	ns	
from set-to-0 to output	!	$ R_L = 2 k\Omega \pm 10\% $ $  2/$	10, 11		56	<u> </u>	
			9		45	ns	
	<u> </u>		10, 11		63		
Propagation delay time,	t <sub>PHL 7</sub>		9		40	ns	
from set-to-9 to $Q_{ extsf{B}}$ or $Q_{ extsf{C}}$			10, 11		56	<u> </u>	
			9		45	ns	
			10, 11		63		
Propagation delay time,	t <sub>PLH7</sub>		9		30	ns	
from set-to-9 to $Q_{ extsf{A}}$ or $Q_{ extsf{D}}$			10, 11		42	<u> </u>	
			9		35	l ns	
			10, 11		49	1	

 $<sup>\</sup>underline{1/}$  Not more than one output should be shorted at a time, and the duration of the short circuit condition should not exceed one second.

## 4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-SID-883 (see 3.1 herein).

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 $<sup>^{2\</sup>prime}$  Propagation delay time testing and maximum clock frequency testing may be performed using either  $_{\text{C}_{\text{I}}}$  = 15 pF or  $_{\text{C}_{\text{L}}}$  = 50 pF. However, the manufacturer must certify and guarantee that the microcircuits meet the switching test limits specified for a 50 pF load.

<sup>3.8 &</sup>lt;u>Verification and review</u>. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

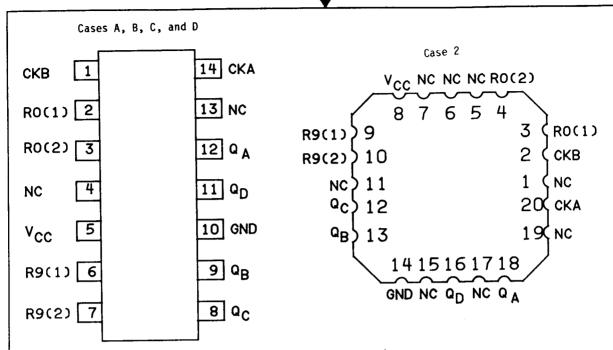


FIGURE 1. Terminal connections

# Reset/count function table

	Rese	t inputs		Output					
R <sub>0(1)</sub>	R <sub>0</sub> (2)	R <sub>9(1)</sub>	R9(2)	QD	QC	QB	QA		
н	Н	L	Х	L	L	L	L		
Н	н	X	L	   L	L	L	L		
Х	x	н	н	Н	L	L	Н		
х	L	x	L		Cou	ınt			
L	X	L	X	-	Count				
   L	X	x	L		Count				
)   X	L	L	x		Count				

- A. Output  $Q_A$  is connected to input B for BCD count. B. Output  $Q_D$  is connected to input A for bi-quinary count. C. H = high level, L = low level, X = irrelevant.

FIGURE 2. Truth table.

	SIZE				DWG NO	•	
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			1	•			

BI-Quinary (5-2) (See note B)

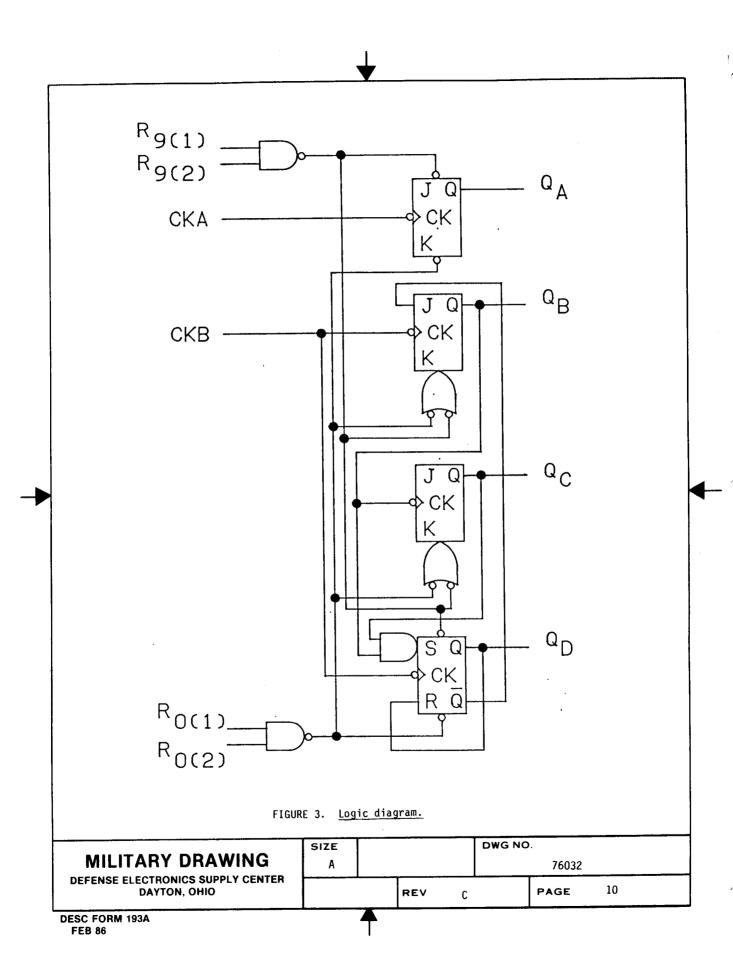
  Count	Output							
 	QA	QD	Q <sub>C</sub>	Q <sub>B</sub>				
0	IL.	L	L	L				
1	ļL	L	L	н	ļ			
2	ļL	L	Н	L				
3	L	L	Н	н	ļ			
4	L	Н	L	L				
5	ļΗ	L	L	L				
   6	!  H	L	L	н	-			
7	ļн	L	Н	L				
   8	Н	L	н	н				
9	   	Н	Ļ	L	1			

BCD count sequence (See note A)

  Count	Output							
   	IQ <sub>D</sub>	QC	Q <sub>B</sub>	Q <sub>A</sub>				
0	ļL	L	L	L	ļ			
1	L	L	L	Н	ļ			
2	L	L	Н	L	ļ			
3	ļL	L	Н	Н	ĺ			
4	L	Н	L	L				
5	L	Н	L	Н				
)   6	L	н	н	L				
7	L	н	Н	н				
l   8	ļH	L	Ĺ	L				
   9 	H I	L	L	н				

FIGURE 2. <u>Truth table</u> - Continued.

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- 4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
  - a. Burn-in test (method 1015 of MIL-STD-883).
    - Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
    - (2)  $T_A = +125^{\circ}C$ , minimum.
  - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

TABLE II. Electrical test requirements.

   MIL-STD-883 test requirements   	Subgroups   (per method   5005, table I) 
  Interim electrical parameters   (method 5004) 	   
	   1*, 2, 3, 9 
  Group A test requirements   (method 5005) 	1 1, 2, 3, 7, 9 1 10, 11**
  Groups C and D end-point  electrical parameters  (method 5005) 	1, 2, 3

- \* PDA applies to subgroup 1.
- \*\* Subgroups 10 and 11, if not tested, shall be guaranteed to the specified limits in table I.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method  $\overline{5005}$  of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
  - 4.3.1 Group A inspection.
    - a. Tests shall be as specified in table II herein.
    - b. Subgroups 4, 5, 6, and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.
    - c. Subgroup 7 tests shall verify the truth table.

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## 4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test (method 1005 of MIL-STD-883) conditions:
  - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
  - (2)  $T_A = +125^{\circ}C$ , minimum.
  - (3) Test duration: 1,000 hours, except as permitted by appendix B of MIL-M-38510 and method 1005 of MIL-STD-883.

### 5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

## 6. NOTES

- 6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
  - 6.2 Replaceability. Replaceability is determined as follows:
    - a. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
    - b. When a QPL source is established, the part numbered device specified in this drawing will be replaced by the microcircuit identified as part number M38510/31501B--.
- 6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, OH 45444, or telephone 513-296-5375.

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6.4 Approved sources of supply. Approved sources of supply are listed herein. Additional sources will be added as they become available. The vendors listed herein have agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECS.

Military dra part number	Military drawing part number		Vendor similar part number <u>1</u> /	Replacement  military specification   part number
7603201AX	2/	3/		M38510/31501BAX
   7603201BX 	2/	3/		M38510/31501BBX
7603201CX	2/	04713   01295	54LS90/BCAJC   SNJ54LS90J 	M38510/31501BCX
7603201DX	2/	04713 01295	   54LS90/BDAJC   SNJ54LS90W 	M38510/31501BDX
76032012X	2/	04713	   54LS90M/B2AJC 	M38510/31501B2X

 $\frac{1}{2}$  Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing. 
2/ Inactive for new design. Use QPL-38510 product. 
3/ No approved source available for this device.

Vendor CAGE number	Vendor name and address				
04713	Motorola, Inc. 7402 South Price Road Tempe, AZ 85283				
01295	Texas Instruments, Inc. P.O. Box 6448 Midland, TX 79701				

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